

## Electronic Patent Application Fee Transmittal

Application Number:	10520444			
Filing Date:	06-Jan-2005			
Title of Invention:	Hygroscopic molding			
First Named Inventor/Applicant Name:	Teruo Uchibori			
Filer:	Raymond D. Smith/Dawn Turner			
Attorney Docket Number:	SAEG103.003APC			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$0 paid	1253	1	1050	1050

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1050</b>